

LP3470 Tiny Power On Reset Circuit

Check for Samples: [LP3470](#)

FEATURES

- Tiny SOT-23-5 Package
- Open Drain Reset Output
- Programmable Reset Timeout Period Using an External Capacitor
- Immune to Short V_{CC} Transients

APPLICATIONS

- Critical μP and μC Power Monitoring
- Intelligent Instruments
- Computers
- Portable/Battery-Powered Equipments

KEY SPECIFICATIONS

- $\pm 1\%$ Reset Threshold Accuracy Over Temperature
- Standard Reset Threshold Voltages: 2.63V, 2.93V, 3.08V, 3.65V, 4.00V, 4.38V, and 4.63V
- Custom Reset Threshold Voltages: For Other Voltages Between 2.4V and 5.0V Contact Your TI Representative
- Very Low Quiescent Current (16 μA typical)
- Reset Valid Down to $V_{CC}=0.5V$

Pin Configuration and Basic Operating Circuit

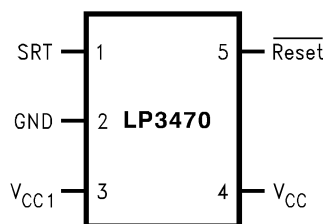


Figure 1. Pin Configuration Top View
See Package Number DBV0005A

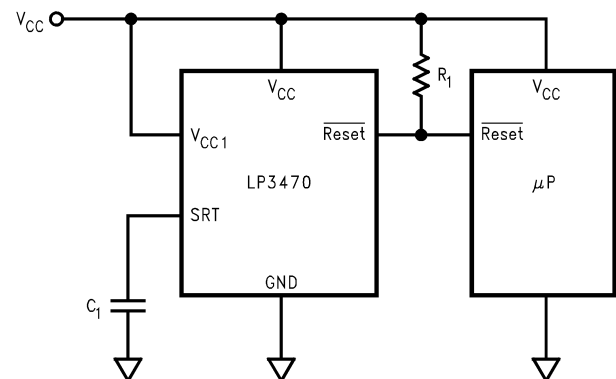


Figure 2. Basic Operating Circuit



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾⁽²⁾

V _{CC} Voltage		–0.3V to +6V
Reset Voltage		–0.3V to +6V
Output Current ($\overline{\text{Reset}}$)		10 mA
Operating Temperature Range	LP3470	–20°C to +85°C
	LP3470I	–40°C to +85°C
Junction Temperature (T _{Jmax})		125°C
Power Dissipation (T _A = 25°C) ⁽³⁾		300 mW
θ _{JA} ⁽³⁾		280°C/W
Storage Temp. Range		–65°C to +150°C
Lead Temp. (Soldering, 5 sec)		260°C
ESD Rating ⁽⁴⁾		2 kV

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Electrical specifications do not apply when operating the device beyond its operating conditions.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (Maximum Junction Temperature), θ_{JA} (Junction to Ambient Thermal Resistance), and T_A (Ambient Temperature). The maximum allowable power dissipation at any temperature is P_{Dmax} = (T_{Jmax} – T_A) / θ_{JA} or the number given in the Absolute Maximum Ratings, whichever is lower.
- (4) The Human Body Model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin.

Electrical Characteristics

Limits in standard typeface are for T_J = 25°C, and limits in **boldface** type apply over the full operating temperature range, unless otherwise specified. V_{CC} = +2.4V to +5.0V unless otherwise noted.

Symbol	Parameter	Conditions	Typ ⁽¹⁾	Min ⁽²⁾	Max ⁽²⁾	Units
V _{CC}	Operating Voltage Range			0.5	5.5	V
I _{CC}	V _{CC} Supply Current	V _{CC} = 4.5V	16		30	μA
V _{RTH}	Reset Threshold Voltage ⁽³⁾	LP3470	V _{RTH}	0.99 V _{RTH} 0.99 V _{RTH}	1.01 V _{RTH} 1.01 V _{RTH}	V
		LP3470I	V _{RTH}	0.99 V _{RTH} 0.985 V _{RTH}	1.01 V _{RTH} 1.015 V _{RTH}	
V _{HYST}	Hysteresis Voltage ⁽⁴⁾		35	15	65	mV
t _{PD}	V _{CC} to Reset Delay	V _{CC} falling at 1 mV/μs	100		300	μs
t _{RP}	Reset Timeout Period ⁽⁵⁾	C ₁ = 1 nF	2	1.0	3.5	ms
V _{OL}	Reset Output Voltage Low	V _{CC} = 0.5V; I _{OL} = 30 μA			0.1	V
		V _{CC} = 1.0V; I _{OL} = 100 μA			0.1	
		V _{CC} = V _{RTH} – 100 mV; I _{OL} = 4 mA			0.4	
R ₁	External Pull-up Resistor		20	0.68	68	kΩ
I _{LEAK}	Reset Output Leakage Current		0.15		1	μA
					6	

- (1) Typical numbers are at 25°C and represent the most likely parametric norm.
- (2) Min. and Max. limits in standard typeface are 100% production tested at 25°C. Min. and Max. limits in boldface are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate TI's Average Outgoing Quality Level (AOQL).
- (3) Factory-trimmed reset thresholds are available in 50 mV increments from 2.4V to 5.0V. Contact your TI representative.
- (4) V_{HYST} affects the relation between V_{CC} and Reset as shown in the timing diagram.
- (5) t_{RP} is programmable by varying the value of the external capacitor (C₁) connected to pin SRT. The equation is: t_{RP} = 2000 × C₁ (C₁ in μF and t_{RP} in ms).

Typical Operating Characteristics

$T_A = +25^\circ\text{C}$, unless otherwise specified.

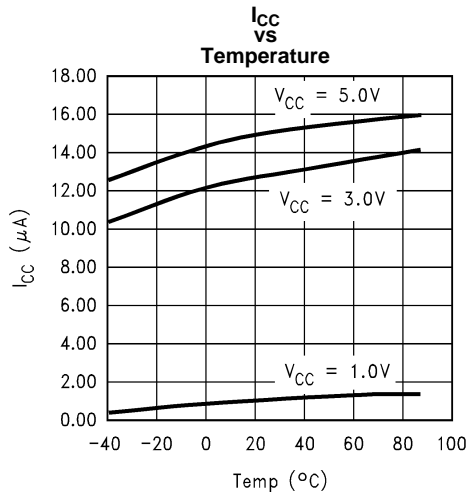


Figure 3.

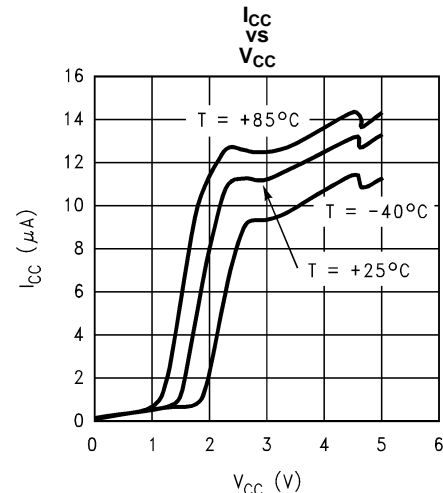


Figure 4.

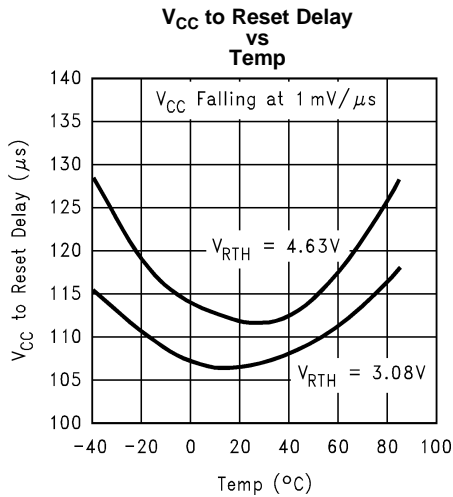


Figure 5.

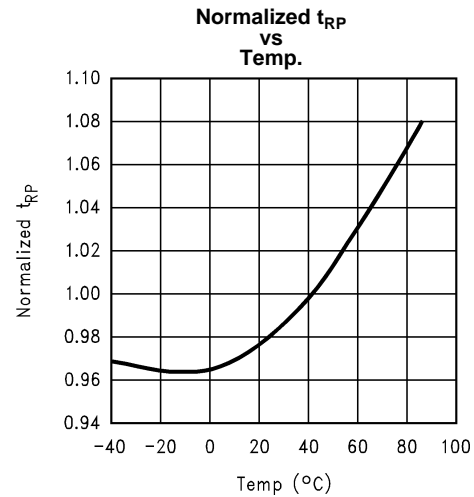


Figure 6.

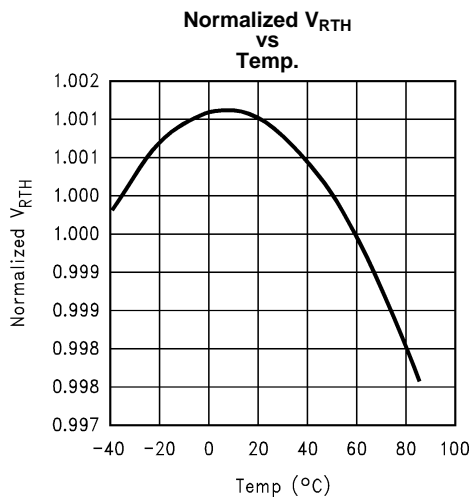


Figure 7.

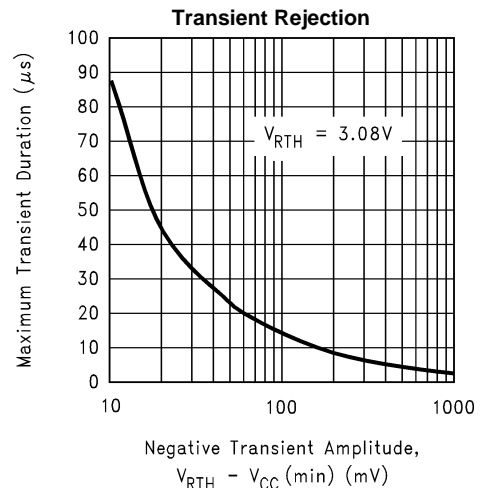
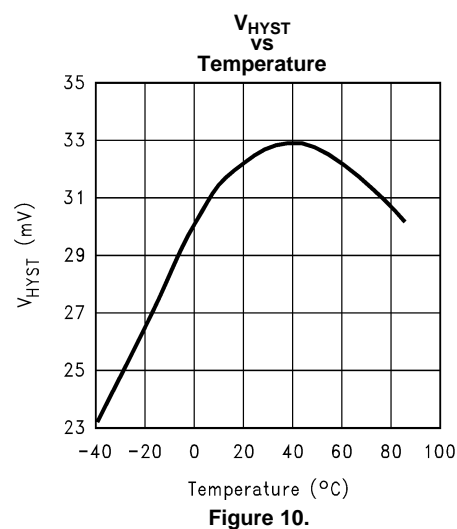
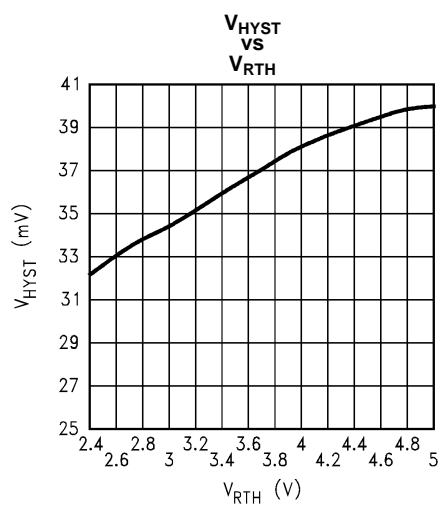


Figure 8.

Typical Operating Characteristics (continued) $T_A = +25^\circ\text{C}$, unless otherwise specified.

PIN DESCRIPTIONS

Pin	Name	Function
1	SRT	Set Reset Time-out Input. Connect a capacitor between this input and ground to select the Reset Time-out period (t_{RP}). $t_{RP} = 2000 \times C_1$ (C_1 in μF and t_{RP} in ms). If no capacitor is connected, leave this pin floating.
2	GND	Ground pin.
3	V_{CC1}	Always connect to pin V_{CC} (Pin 4).
4	V_{CC}	Supply voltage, and reset threshold monitor input.
5	$\overline{\text{Reset}}$	Open-Drain, Active-Low reset output. Connect to an external pull-up resistor. $\overline{\text{Reset}}$ changes from high to low whenever the monitored voltage (V_{CC}) drops below the reset threshold voltage (V_{RTH}). Once V_{CC} exceeds V_{RTH} , $\overline{\text{Reset}}$ remains low for the reset timeout period (t_{RP}) and then goes high.

Functional Block Diagram

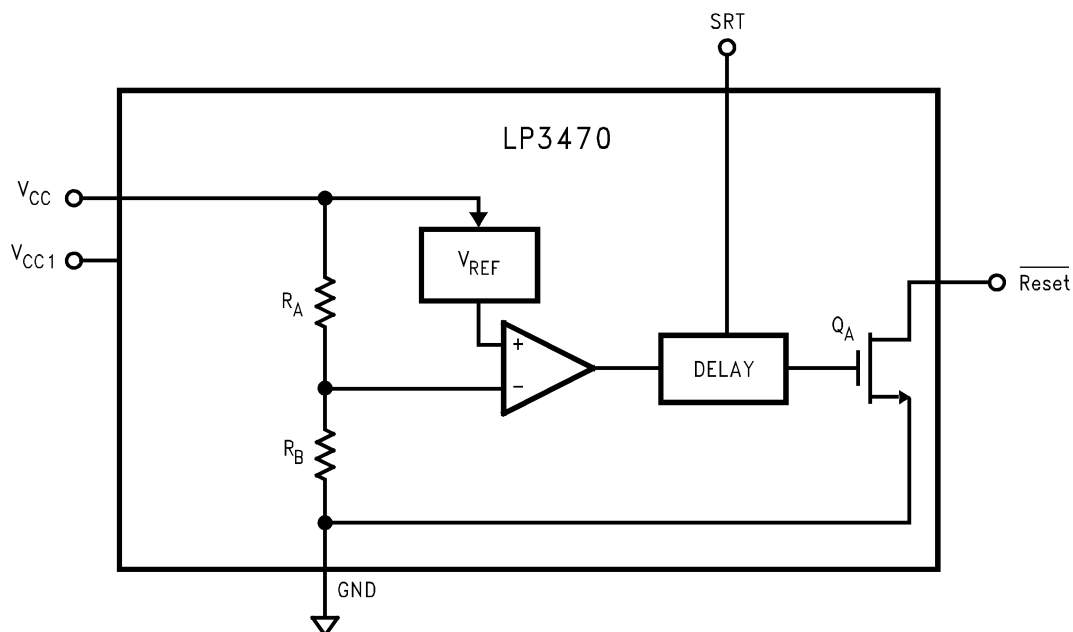


Figure 11.

APPLICATION INFORMATION

RESET TIMEOUT PERIOD

The Reset Timeout Period (t_{RP}) is programmable using an external capacitor (C_1) connected to pin SRT of LP3470. A Ceramic chip capacitor rated at or above 10V is sufficient. The Reset Timeout Period (t_{RP}) can be calculated using the following formula:

$$t_{RP} \text{ (ms)} = 2000 \times C_1 \text{ (}\mu\text{F)} \quad (1)$$

For example a C_1 of 100 nF will achieve a t_{RP} of 200 ms. If no delay due to t_{RP} is needed in a certain application, the pin SRT should be left floating.

RESET OUTPUT

In applications like microprocessor (μP) systems, errors might occur in system operation during power-up, power-down, or brownout conditions. It is imperative to monitor the power supply voltage in order to prevent these errors from occurring.

The LP3470 asserts a reset signal whenever the V_{CC} supply voltage is below a threshold (V_{RTH}) voltage. $\overline{\text{Reset}}$ is ensured to be a logic low for $V_{CC} > 0.5\text{V}$. Once V_{CC} exceeds the reset threshold, the reset is kept asserted for a time period (t_{RP}) programmed by an external capacitor (C_1); after this interval $\overline{\text{Reset}}$ goes to logic high. If a brownout condition occurs (monitored voltage falls below the reset threshold minus a small hysteresis), $\overline{\text{Reset}}$ goes low. When V_{CC} returns above the reset threshold, $\overline{\text{Reset}}$ remains low for a time period t_{RP} before going to high.

PULL-UP RESISTOR SELECTION

The LP3470's $\overline{\text{Reset}}$ output structure is a simple open-drain N-channel MOSFET switch. A pull-up resistor (R_1) should be connected to V_{CC} .

R_1 should be large enough to limit the current through the output MOSFET (Q_1) below 10 mA. A resistor value of more than 680Ω ensures this. R_1 should also be small enough to ensure a logic high while supplying all the leakage current through the Reset pin. A resistor value of less than $68\text{k}\Omega$ satisfies this condition. A typical pull-up resistor value of $20\text{ k}\Omega$ is sufficient in most applications.

NEGATIVE-GOING V_{CC} TRANSIENTS

The LP3470 is relatively immune to short duration negative-going V_{CC} transients (glitches). The Typical Operating Characteristics show the Maximum Transient Duration vs. Negative Transient Amplitude (graph titled Transient Rejection), for which reset pulses are not generated. This graph shows the maximum pulse width a negative-going V_{CC} transient may typically have without causing a reset pulse to be issued. As the transient amplitude increases (i.e. goes farther below the reset threshold), the maximum allowable pulse width decreases. A $0.1\text{ }\mu\text{F}$ bypass capacitor mounted close to V_{CC} provides additional transient immunity.

Timing Diagram

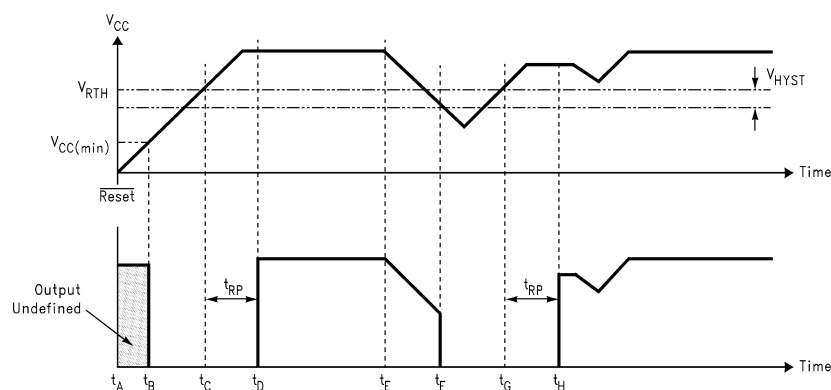


Figure 12.

Typical Application Circuit

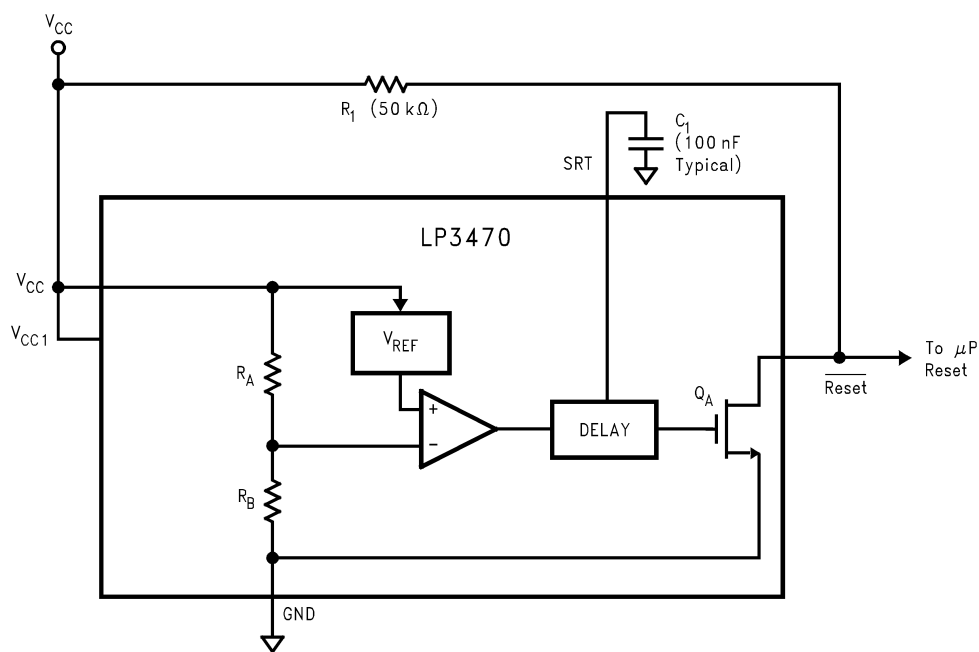


Figure 13.

REVISION HISTORY

Changes from Revision E (March 2013) to Revision F	Page
<ul style="list-style-type: none"> Changed layout of National Data Sheet to TI format 	7

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LP3470IM5-2.63	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	D25C	
LP3470IM5-2.63/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D25C	Samples
LP3470IM5-2.75	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI		D38C	
LP3470IM5-2.75/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		D38C	Samples
LP3470IM5-2.83/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		D39C	Samples
LP3470IM5-2.93	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	D26C	
LP3470IM5-2.93/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D26C	Samples
LP3470IM5-3.08	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	D28C	
LP3470IM5-3.08/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D28C	Samples
LP3470IM5-3.65/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D37C	Samples
LP3470IM5-4.00	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	D29C	
LP3470IM5-4.00/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D29C	Samples
LP3470IM5-4.38	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	D30C	
LP3470IM5-4.38/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D30C	Samples
LP3470IM5-4.63	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	D31C	
LP3470IM5-4.63/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D31C	Samples
LP3470IM5-4.8/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		D15C	Samples
LP3470IM5X-2.63	NRND	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 85	D25C	
LP3470IM5X-2.63/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D25C	Samples
LP3470IM5X-2.83/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		D39C	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LP3470IM5X-2.93/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D26C	Samples
LP3470IM5X-3.08	NRND	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 85	D28C	
LP3470IM5X-3.08/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D28C	Samples
LP3470IM5X-4.00	NRND	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 85	D29C	
LP3470IM5X-4.00/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D29C	Samples
LP3470IM5X-4.38	NRND	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 85	D30C	
LP3470IM5X-4.38/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D30C	Samples
LP3470IM5X-4.63	NRND	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 85	D31C	
LP3470IM5X-4.63/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D31C	Samples
LP3470M5-2.63	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-20 to 85	D25B	
LP3470M5-2.63/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D25B	Samples
LP3470M5-2.93	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-20 to 85	D26B	
LP3470M5-2.93/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D26B	Samples
LP3470M5-3.08	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-20 to 85	D28B	
LP3470M5-3.08/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D28B	Samples
LP3470M5-4.00/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D29B	Samples
LP3470M5-4.38/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D30B	Samples
LP3470M5-4.63	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-20 to 85	D31B	
LP3470M5-4.63/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D31B	Samples
LP3470M5X-2.93/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D26B	Samples
LP3470M5X-3.08/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D28B	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LP3470M5X-4.00/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D29B	Samples
LP3470M5X-4.63/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-20 to 85	D31B	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3470IM5-2.63	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-2.63/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-2.75	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-2.75/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-2.83/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-2.93	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-2.93/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-3.08	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-3.08/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-3.65/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.00	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.00/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.38	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.38/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.63	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.63/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5-4.8/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-2.63	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3470IM5X-2.63/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-2.83/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-2.93/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-3.08	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-3.08/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-4.00	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-4.00/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-4.38	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-4.38/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-4.63	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470IM5X-4.63/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-2.63	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-2.63/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-2.93	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-2.93/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-3.08	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-3.08/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-4.00/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-4.38/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-4.63	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5-4.63/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5X-2.93/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5X-3.08/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5X-4.00/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LP3470M5X-4.63/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3470IM5-2.63	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-2.63/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-2.75	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-2.75/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-2.83/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-2.93	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-2.93/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-3.08	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-3.08/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-3.65/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.00	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.00/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.38	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.38/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.63	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.63/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5-4.8/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470IM5X-2.63	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-2.63/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-2.83/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3470IM5X-2.93/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-3.08	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-3.08/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-4.00	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-4.00/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-4.38	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-4.38/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-4.63	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470IM5X-4.63/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470M5-2.63	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-2.63/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-2.93	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-2.93/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-3.08	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-3.08/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-4.00/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-4.38/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-4.63	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5-4.63/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LP3470M5X-2.93/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470M5X-3.08/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470M5X-4.00/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LP3470M5X-4.63/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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